



PK640 (v1.0) April 4, 2014

100% Material Declaration Data Sheet for Spartan 3A DSP CSG484 Package

Average Weight: 1.3264g

Component	Substance Description	CAS Number or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.048956	3.691
	Silicon	7440-21-3	100.00		0.048956	
Silver Epoxy					0.014829	1.118
	Silver	7440-22-4	77.50		0.011492	
	Bismaleimide monomer	Trade Secret	15.00		0.002224	
	Acrylate monomer	Trade Secret	7.50		0.001112	
Mold Compound					0.453644	34.201
	Epoxy Resin	Trade Secret	7.50		0.034023	
	Phenol Resin A	9003-35-4	3.00		0.013609	
	Phenol Resin B	Trade Secret	3.00		0.013609	
	Silica(Amorphous)A	60676-86-0	67.95		0.308251	
	Silica(Amorphous)B	7631-86-9	15.00		0.068047	
	Metal Hydroxide	Trade Secret	3.00		0.013609	
	Carbon Black	1333-86-4	0.55		0.002495	
Copper Wire					0.003811	0.287
	Copper	7440-50-8	98.25		0.003744	
	Palladium	7440-05-3	1.75		0.000067	
Solder Ball					0.171033	12.895
	Tin	7440-31-5	95.50		0.163337	
	Silver	7440-22-4	4.00		0.006841	
	Copper	7440-50-8	0.50		0.000855	
Substrate					0.634127	47.808
	Gold	7440-57-5	0.12		0.000754	
	Nickel	7440-02-0	1.10		0.006956	
	Copper Foil	7440-50-8	52.40		0.332302	
	Copper Plating	7440-50-8	4.76		0.030201	
	BT Core	65997-17-3 / 105391-33-1 / 25722-66-1 / 9003-36-5 / 21645-51-2	37.02		0.234740	
	Solder Mask	34590-94-8 / 7727-43-7	4.60		0.029174	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
04/04/14	1.0	Initial Xilinx release.

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